

AMENDMENTS TO CLAIMS

1. (Currently Amended) A method comprising:
forming a chemically soluble coating on a plurality of exposed contacts on a surface of a circuit substrate to a thickness greater than a distance of surface protrusion of a portion of the plurality of contacts;
scribing ~~the surface of~~ through the substrate along scribe areas; and
after scribing, removing a portion of the coating by a dissolution process to expose the plurality of contacts.
2. (Currently Amended) The method of claim 1, wherein each of a portion of the plurality of contacts comprise protruding bumps on the surface ~~and forming the coating comprises forming the coating to a thickness greater than a distance of surface protrusion of the portion of the plurality of contacts.~~
3. (Original) The method of claim 2, wherein the coating has a thickness of 5 to 35 microns.
4. (Original) The method of claim 2, further comprising sawing the substrate along the scribed areas.
5. (Original) The method of claim 4, wherein sawing and removing a portion of the coating are done simultaneously.
6. (Original) The method of claim 1, wherein removing a portion of the coating comprises exposing the plurality of contacts.
7. (Original) The method of claim 6, wherein removing a portion of the coating comprises removing the entire portion.
8. (Original) The method of claim 1, wherein a material of the chemically soluble coating is selected from the group consisting of methyl cellulose, polyvinyl alcohol, and resin flux.

9. (Currently Amended) A method comprising:
forming a circuit structure ~~comprises~~ comprising a plurality of exposed contacts on a surface, a location of the exposed contacts defined by a plurality of scribe streets;
forming a coating comprising a chemically soluble material on the exposed contacts to a thickness greater than a distance of surface protrusion of a portion of the plurality of contacts;
~~scribing the surface of~~ through the substrate along the scribe streets; and
after scribing, removing the coating from an area on the contacts by a dissolution process.
10. (Original) The method of claim 9, further comprising, after scribing, sawing the substrate along the scribe streets.
11. (Original) The method of claim 10, wherein sawing and removing the coating are done simultaneously.
12. (Original) The method of claim 10, wherein removing the coating comprises removing the entire coating.
13. (Original) The method of claim 10, wherein the material of the coating is selected from the group consisting of methyl cellulose, polyvinyl alcohol, and resin flux.
14. (Currently Amended) A method comprising:
coating a surface of a circuit substrate comprising a plurality of exposed contacts with a chemically soluble material;
scribing the surface of the substrate along scribe areas;
removing the coating to expose the plurality of contacts by a dissolution process; and
sawing the substrate in the scribe areas, wherein sawing and removing the coating are done simultaneously.
15. (Canceled)

16. (Original) The method of claim 15, wherein the material of the coating is selected from the group consisting of methyl cellulose, polyvinyl alcohol, and resin flux.